

Please note that Cypress is an Infineon Technologies Company.

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

Dimensions in mm

Reference Jedec MO-192

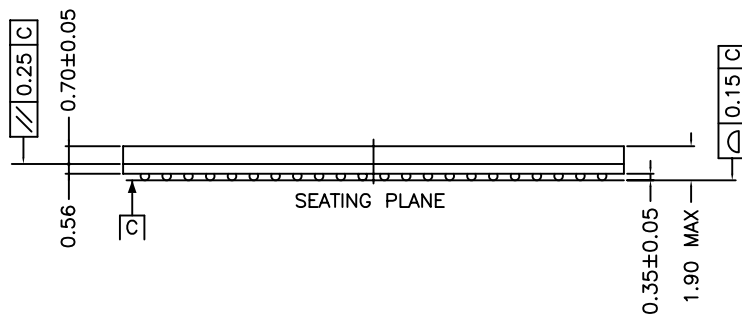
Package Weight – Refer to PMDD spec

TOP VIEW

A1 CORNER

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22

A
B
C
D
E
F
G
H
J
K
L
M
N
P
R
T
U
V
W
Y
AA
AB



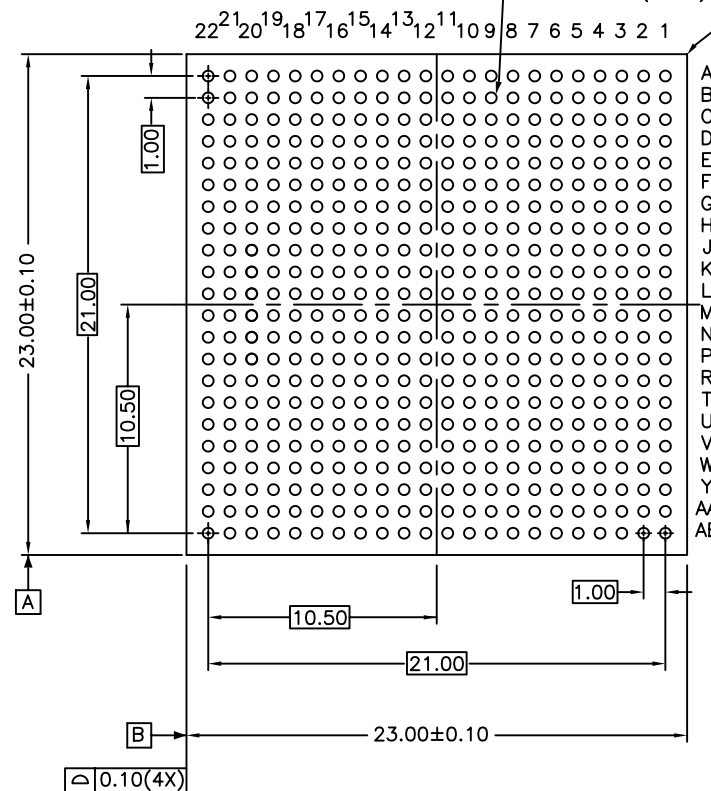
REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	101258	NEW RELEASE	05/25/00	N/A
1	-	*A	106856	CHG. DIM. ON BALL HEIGHT & FLATNESS TOL.	05/01/01	N/A
1	-	*B	115630	CHG. DIM. ON BALL HEIGHT/ADD SUBSTRATE DIM./ADD MOLD CAP DIM.	05/14/02	N/A
1	-	*C	127000	CORRECT LEAD COPLANARITY DIM. TO 0.15	05/14/03	N/A
1	-	*D	128700	CHG. BALL SIZE, BALL HEIGHT, LEAD COPLANARITY AND TOTAL PKG. HEIGHT/ ADD JEDEC NO./ CHANGE TITLE.	07/23/03	N/A
1	-	*E	360958	Flatness changes to 0.15. Add pkg weight.	05/06/05	N/A
1	-	*F	2758054	Change ball diameter and height. Update drawing to new format.	08/31/09	N/A
1	-	*G	2813799	Changed to a standard template.	11/27/09	QAD
1	-	*H	3353048	Update spec for Sunset Review, no change.	08/24/11	QAD
1	-	*I	3726298	Changed package weight reference from 1.3grams to "refer to PMDD spec"	08/28/12	QAD


BOTTOM VIEW

Ø0.05	M	C
Ø0.25	M	C

A1 CORNER

Ø0.45±0.05(484X)



UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE:		DESIGNED BY M.L.A.	DATE 08/31/09	 CYPRESS Company Confidential	
DECIMALS .XX ± 0.05 .XXX ± .XXXX ±		DRAWN BY M.L.A.	DATE 08/31/09		
ANGLES ± 1°		CHECKED BY XANC	DATE 08/28/12	TITLE PACKAGE OUTLINE, 484L FBGA 23X23X1.9 MM BB484	
MATERIAL N/A		APPROVED BY QAD	DATE 08/28/12		
FINISH N/A		APPROVED BY EDCA	DATE 08/28/12	SIZE A	PART NO. BB484
		APPROVED BY PRC	DATE 08/28/12	DWG NO 51-85124	REV *
				SCALED TO FIT N/A	SHEET 1 OF 1

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